

ABSTRACT

A chip capacitor 20 is provided in a core substrate 30 of a printed circuit board 10. This makes it possible to shorten a distance between an IC chip 90 and the chip capacitor 20 and to reduce loop inductance. Since the core substrate 30 is constituted by providing a first resin substrate 30a, a second resin substrate 30b and a third resin substrate 30c in a multilayer manner, the core substrate 30 can obtain sufficient strength.